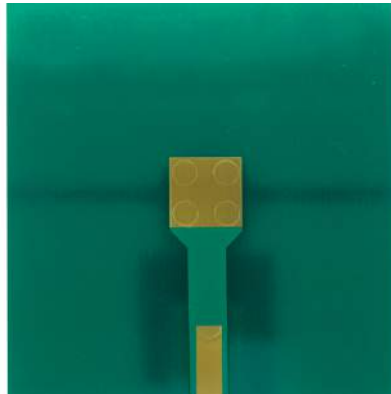
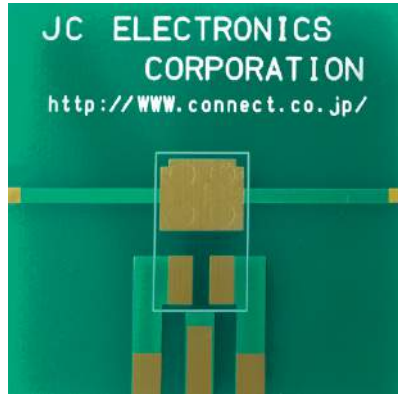


Heat Dissipation Substrate

Light weight, high efficiency in heat exhaustion
Applicable to a variety of purposes including Power Supply Board, In-vehicle equipments, and so on.
High performance heat dissipation



Performance

Temperature Cycle

: $-65 \pm 3^\circ\text{C}$ 30min
: $125 \pm 3^\circ\text{C}$ 30min after 500 cycle

Pin Flatness

: Components side $+0.03 \sim 0.05\text{mm}$ with
: Soldering side $+0.1 \sim 0.05\text{mm}$ with

Pin Retention Force

: No falling out

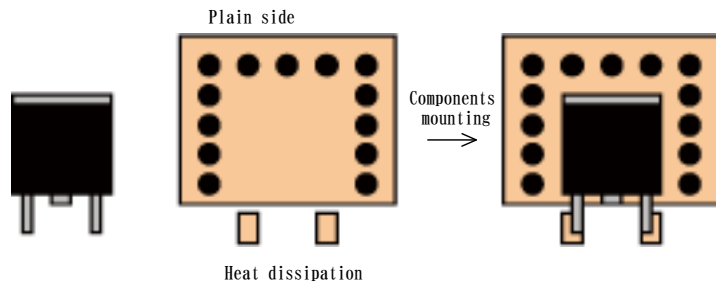
Pre Processing

: Temperature 40°C Humidity 90% Co
: \times Reflow two times

Reflow Resistance

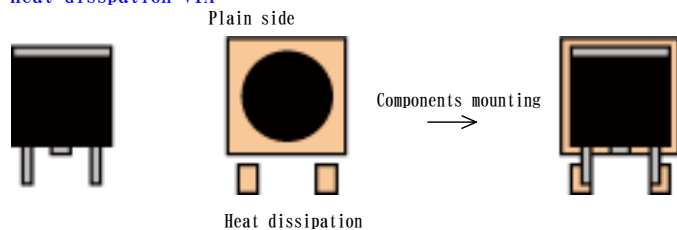
: Conductor float, Delamination, No

Conventional Substrate



Heat is dissipated on the plain side and through Via hole.

Heat dissipation VIA



Efficiency in heat dissipation with small footprint, electrical current can be applied.
Ordinary Via $\phi 1.5\text{mm} \dots 1.5\text{A}$
Filling in with Copper Pin $\phi 1.5\text{mm}$
 $\dots 10\text{A}$ can be applied.



In combination with a heat sink more heat dissipation effect can be obtained.

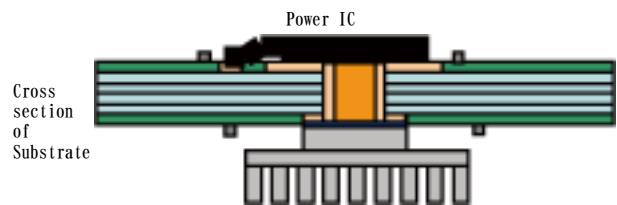
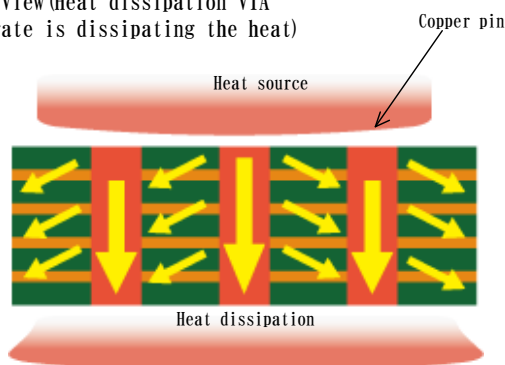


Image View (Heat dissipation VIA Substrate is dissipating the heat)



Heat diffusion sheet and copper are laminated.
Thermal Conductivity $1700\text{w/m}\cdot\text{k}$
Proportion 2.1g/cm^3
(8 times higher than aluminum, 4 times higher than copper in thermal conductivity)